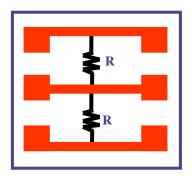
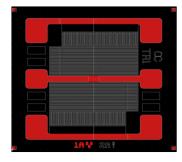
Thin Film Center-Tapped Silicon Resistor Chip

OnChip Devices' TR is a miniature dual resistor network with a common pad in the center. This silicon resistor chip is built using the high reliable Tantalum Nitride resistor material. This product offers a very high degree of stability, extremely low Temperature Coefficient of Resistance and exceptionally low noise.

Electrical Specifications							
Parameter	Conditions						
Temperature Coefficient of Resistance	-55°C to 125°C	±100ppm/°C	Max				
Operating Voltage	-55°C to 125°C	100Vdc	Max				
Power Rating (per resistor)	@ 70°C (Derate linearly to zero @ 150°C)	250mw	Max				
Thermal Shock	Method 107 MIL-STD-202F	±0.5% @ΔR	Max				
High Temperature Exposure	100 Hrs @ 150°C Ambient	±0.25% ΔR	Max				
Moisture Resistance	Method 106 MIL-STD-202F	±0.5% ΔR	Max				
Life	Method 108 MIL-STD-202F (125°C/1000hr)	±0.5% ΔR	Max				
Noise	Method 308 MIL-STD-202F	-25dB	Max				
	≥250 KΩ	-20dB					
Centertap Tolerance	$R_1/R_2 @ 25^{\circ}C$	±1.0%					
Insulation Resistance	@ 25°C	$1 \times 10^{12} \Omega$	Min				





Bonding Area Format

Die Size: 30±3 mils

square

Bonding Pads: 4x4 mils typical

Values	
--------	--

From 4.7Ω to 1 meg Ω for each resistor. Values >1 meg ohms use proprietary resistor material.

Mechanical Specifications				
Substrate	Silicon 10±2 mils thick			
Isolation Layer	SiO ₂ 10,000Å thick, min			
Backing	Lapped (gold optional)			
Metalization	Aluminium 10,000Å thick, min (15,000Å gold optional)			

Packaging

Two inch square trays of 400 chips maximum is standard.

Notes

- 1. Code boxes for alpha numeric laser marking are available
- 2. Resistor Pattern may vary from one value to another.

Part Number Designation								
TR	1002	F	Α	G	W	Р		
Series	Value	Tolerance	TCR	Bond Pads	Backing	Ratio Tolerance		
	First 3 digits are significant value. Last digit represents number of zeros (Ex: 1001 = 1k-ohms). R indicates decimal point.	$D = \pm 0.5\%$	No letter = ±100ppm/°C	G = Gold	W = Gold	No Letter = ±1%		
		F = ±1%	$A = \pm 50$ ppm/°C	No Letter = Aluminium	L = Lapped	$P = \pm 0.5\%$		
		G = ±2%	$B = \pm 25 ppm/^{\circ}C$		No Letter = Either			
		J = ±5%						
		K = ±10%						
		$M = \pm 20\%$						